

Package Information: TO263-5F

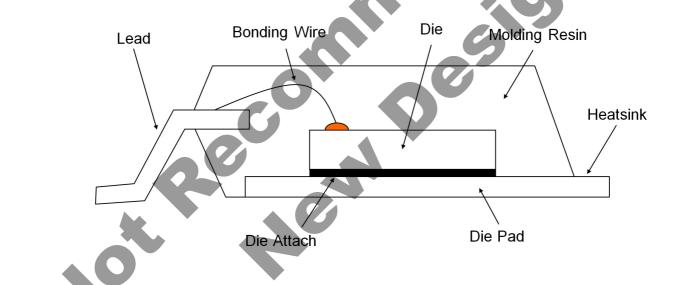
1. Package Information

Package Name TO263-5F
Type TO
Pin Count 5

Outline Dimension EX001-0066 Drowing No.

Package Weight [g] 1.52
Lead Finish Pure Tin
MSL Level Level3

2. Package Structure



Package Information

3. Packing Specification

TO263-5F

3.1 Packing form, Quantity, PIN1 Orientation

Packing Form Tape&Reel
Packing Quantity [pcs] 500
PIN 1 Orientation E2

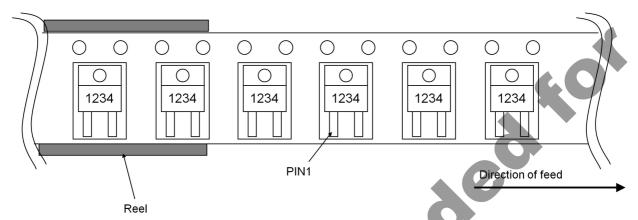


Fig.1 Quadrant Assignments for PIN 1 Orientation in Tape

3.2 Use material

Item	Material
Embossed carrier tape	PS
Cover tape	PET+PE
Reel	PS
Desiccant	Silicagel
Envelope	Aluminum-laminated
Air cap	PÈ
Unit box	Cardboard
Shipping box	Cardboard

3.3 Leader specification

No component pockets are 480 mm or more.

3.4 Trailer specification

No component pockets are 120 mm or more. Tape is free from reel.

3.5 Peelback strength

Cover tape peelback strength is 0.2 N to 0.7 N.

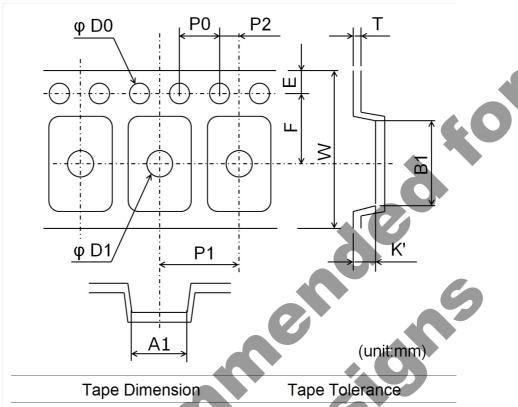
Peelback
Peelback speed
300±10mm/min

Fig. 2 Test method

3.6 Missing Ics

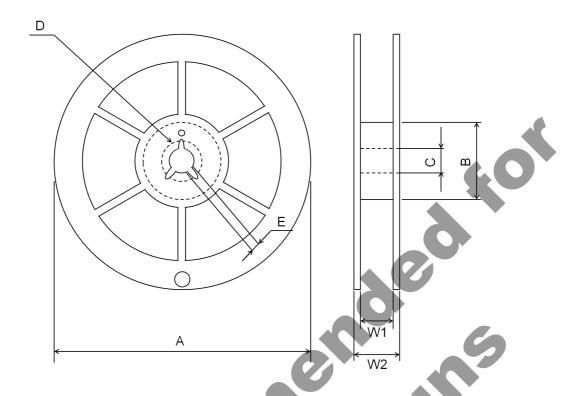
- (1) No consecutive dropouts.
- (2) A maximun 0.1 % of specified number of products in each packing may be missing.

3.7 Tape and Reel Specification3.7.1 Tape Dimension



	Tape Dimension	Tape Tolerance
A1	10.6	±0.1
B1	15.8	≠ 0.1
D0	φ1.55	±0.05
D1	φ1.6	±0.05
E	1.75	±0.1
F	11.5	±0.1
K'	4.90	±0.1
P0	4.00	±0.1
P1	12.0	±0.1
P2	2.00	±0.1
Т	0.30	±0.05
W	24.0	±0.3

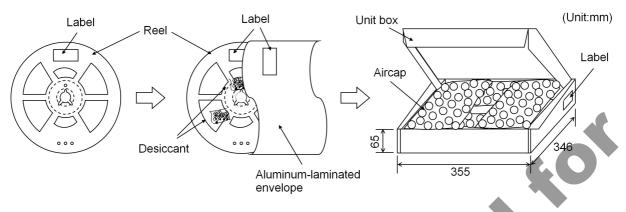
3.7.2 Reel Dimension



		(Gritchin)
	Reel Dimension	Reel Tolerance
Α	330	±2.0
В	80	±1.0
C	13	±0.2
	21	±0.8
Е	2	±0.5
W	1 25.5	±1.0
W	2 29.5	±1.0

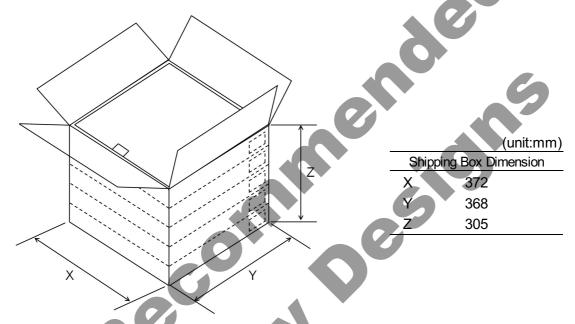
3.8 Packing Method

1 reel(s) or less per unit box

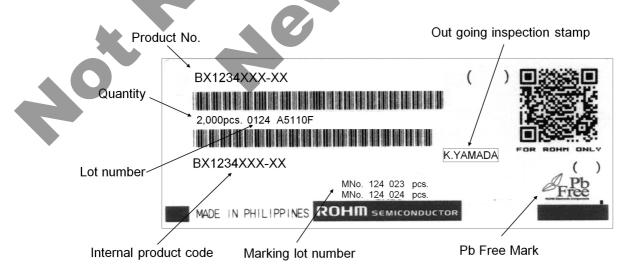


3.9 Packing Style

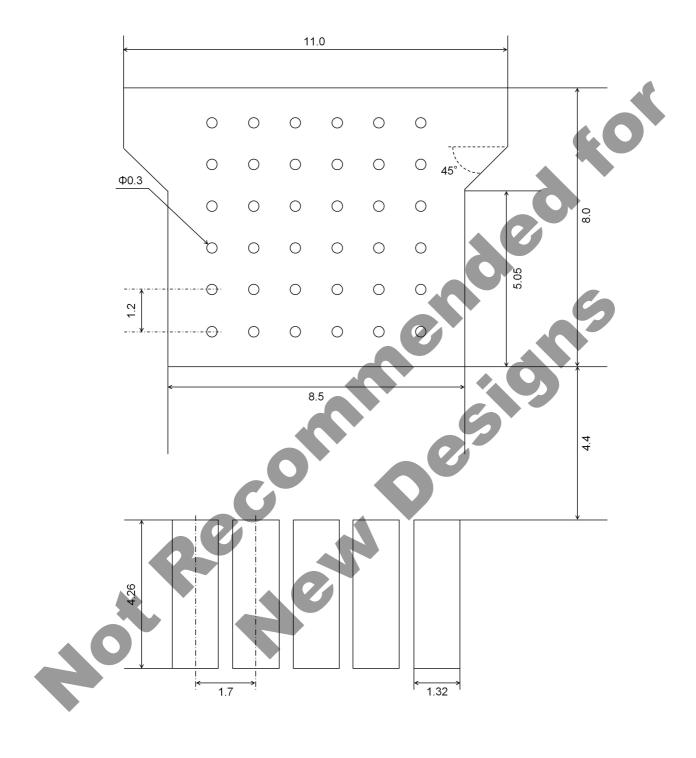
5 unit boxes or less per shipping box



3.10 Label Specification



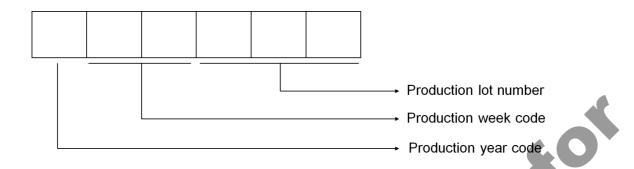
4. Footprint dimensions



(unit:mm)

In actual design, please optimize in accordance with the situation of your board design and soldering condition.

5. Marking Specification



6. Storage conditions

6.1 Storage environment

Recommended storage conditions

	Min.	Max.	Unit
Temperature	5	30	°C
Humidity	40	70	% RH

6.2 Storage period

	Min.	Max.	Unit
Storage period	-	1	year

6.3 Specified storage period until soldering

	Min.	Max.	Unit
Acceptable time	-	168	hour

The above value is a time from opening the moisture-proof packaging until the soldering.

Cases where it is necessary to perform the drying process is the following.

Case 1: in excess of the above-mentioned "Acceptable time"

Case 2: it has passed more than a year not open

Recommended the dry process conditions

	Temperature [°C]	Time [hour]
Reel ^(Note1)	60	48
Other Heat-proof container	125	24

(Note1) When carrying out the dry process in a "Reel" state, the peelback strength will change. Please refer to the following values:

	Min.	Max.	Unit
Peelback strength	0.2	0.9	N

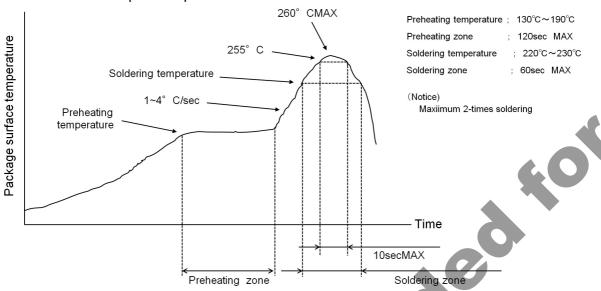
The drying process is the impact on the solderability because the oxidation of the terminal portion will occur. Therefore, specify the maximum times of the dry processing as follows:

Recommended execution count of the dry process

	Min.	Max.	Unit
Execution count	-	2	times

7. Soldering conditions

7.1 Recommended temperature profile for reflow



7.2 Recommended condition for wave soldering

Preheating temperature : 120 °C to 150 °C

Preheating time : 60 sec MAX

Soldering temperature : 260 $^{\circ}$ C \pm 3 $^{\circ}$ C

Soldering time : 12 sec MAX

Notes for wave soldering

- (1) Soldering time is provided for total soldering time in case of dual wave soldering.
- (2) Do not use other soldering methods with wave soldering.
- (3) Recommend to clean the board to eliminate flux, solder waste, and other impurities for reliability, after soldering.
- (4) Optimize soldering condition to prevent solder bridging.

7.3 Recommended condition for solder iron

Solder iron temperature : 380 °C or less
Mounting time : 4 sec or less

Notes

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